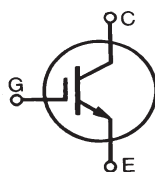


# XPT™ 650V IGBT GenX4™

## IXXH110N65C4

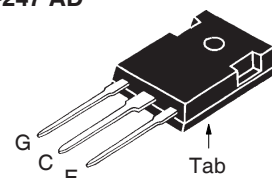
Extreme Light Punch Through  
IGBT for 20-60 kHz Switching



$$\begin{aligned} V_{CES} &= 650V \\ I_{C110} &= 110A \\ V_{CE(sat)} &\leq 2.35V \\ t_{fi(typ)} &= 35ns \end{aligned}$$

Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_J = 25^\circ\text{C to } 175^\circ\text{C}$	650	V
$V_{CGR}$	$T_J = 25^\circ\text{C to } 175^\circ\text{C}, R_{GE} = 1M\Omega$	650	V
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ\text{C}$ (Chip Capability)	235	A
$I_{LRMS}$	Terminal Current Limit	160	A
$I_{C110}$	$T_C = 110^\circ\text{C}$	110	A
$I_{CM}$	$T_C = 25^\circ\text{C}, 1\text{ms}$	600	A
<b>SSOA</b>	$V_{GE} = 15\text{V}, T_{VJ} = 150^\circ\text{C}, R_G = 2\Omega$	$I_{CM} = 220$	A
<b>(RBSOA)</b>	Clamped Inductive Load	@ $V_{CE} \leq V_{CES}$	
$t_{sc}$	$V_{GE} = 15\text{V}, V_{CE} = 360\text{V}, T_J = 150^\circ\text{C}$	10	$\mu\text{s}$
<b>(SCSOA)</b>	$R_G = 10\Omega$ , Non Repetitive		
$P_C$	$T_C = 25^\circ\text{C}$	880	W
$T_J$		-55 ... +175	$^\circ\text{C}$
$T_{JM}$		175	$^\circ\text{C}$
$T_{stg}$		-55 ... +175	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering	300	$^\circ\text{C}$
$T_{SOLD}$	1.6 mm (0.062in.) from Case for 10s	260	$^\circ\text{C}$
$M_d$	Mounting Torque	1.13/10	Nm/lb.in.
<b>Weight</b>		6	g

TO-247 AD



G = Gate      C = Collector  
E = Emitter    Tab = Collector

### Features

- Optimized for 20-60kHz Switching
- Square RBSOA
- Avalanche Capability
- Short Circuit Capability
- International Standard Package

### Advantages

- High Power Density
- 175 $^\circ\text{C}$  Rated
- Extremely Rugged
- Low Gate Drive Requirement

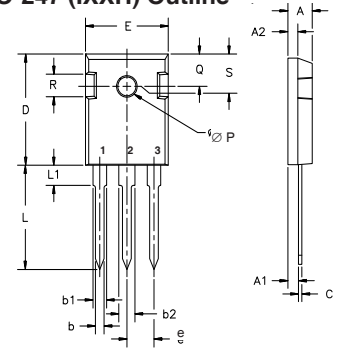
### Applications

- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts
- High Frequency Power Inverters

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{CES}$	$I_C = 250\mu\text{A}, V_{GE} = 0\text{V}$	650		V
$V_{GE(th)}$	$I_C = 4\text{mA}, V_{CE} = V_{GE}$	4.0		6.5 V
$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0\text{V}$ $T_J = 150^\circ\text{C}$			10 $\mu\text{A}$ 500 $\mu\text{A}$
$I_{GES}$	$V_{CE} = 0\text{V}, V_{GE} = \pm 20\text{V}$			$\pm 100$ nA
$V_{CE(sat)}$	$I_C = 110\text{A}, V_{GE} = 15\text{V}$ , Note 1 $T_J = 150^\circ\text{C}$		2.06 2.50	2.35 V V

Symbol Test Conditions ( $T_J = 25^\circ\text{C}$ Unless Otherwise Specified)		Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$I_C = 60\text{A}, V_{CE} = 10\text{V}, \text{Note 1}$	30	52	S
$C_{ies}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$		5500	pF
$C_{oes}$			267	pF
$C_{res}$			80	pF
$Q_{g(on)}$	$I_C = 110\text{A}, V_{GE} = 15\text{V}, V_{CE} = 0.5 \cdot V_{CES}$		167	nC
$Q_{ge}$			44	nC
$Q_{gc}$			63	nC
$t_{d(on)}$	<b>Inductive load, <math>T_J = 25^\circ\text{C}</math></b> $I_C = 55\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 400\text{V}, R_G = 2\Omega$ Note 2		30	ns
$t_{ri}$			45	ns
$E_{on}$			2.50	mJ
$t_{d(off)}$			110	ns
$t_{fi}$			35	ns
$E_{off}$			0.63	1.05 mJ
$t_{d(on)}$	<b>Inductive load, <math>T_J = 150^\circ\text{C}</math></b> $I_C = 55\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 400\text{V}, R_G = 2\Omega$ Note 2		26	ns
$t_{ri}$			45	ns
$E_{on}$			3.55	mJ
$t_{d(off)}$			120	ns
$t_{fi}$			40	ns
$E_{off}$			0.90	mJ
$R_{thJC}$			0.17	$^\circ\text{C}/\text{W}$
$R_{thCS}$		0.21		$^\circ\text{C}/\text{W}$

TO-247 (IXXH) Outline



Terminals: 1 - Gate 2 - Collector  
3 - Emitter

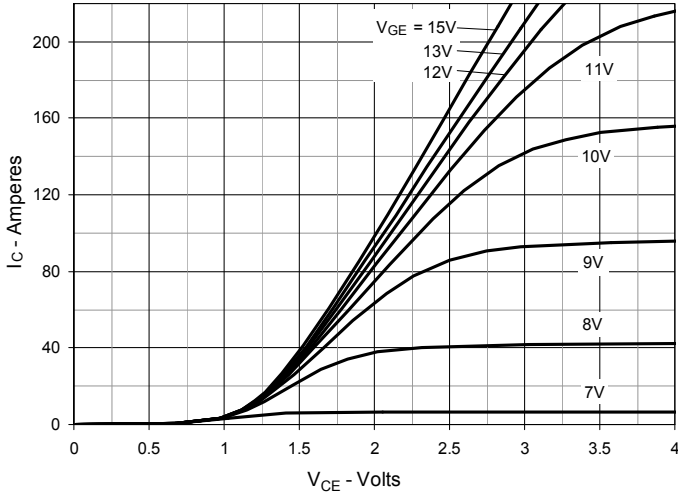
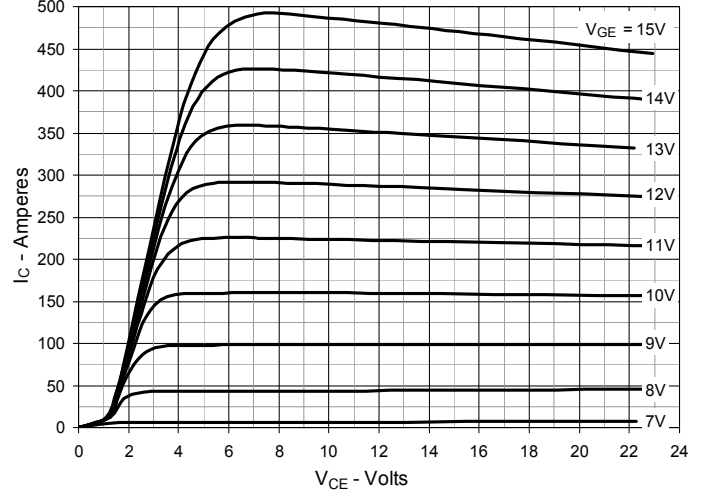
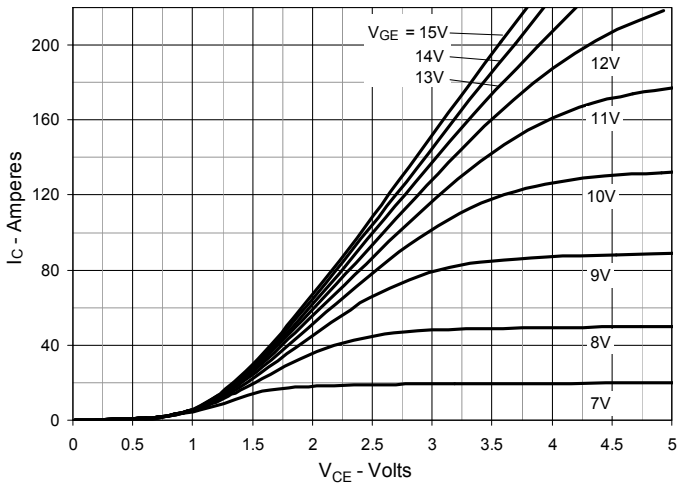
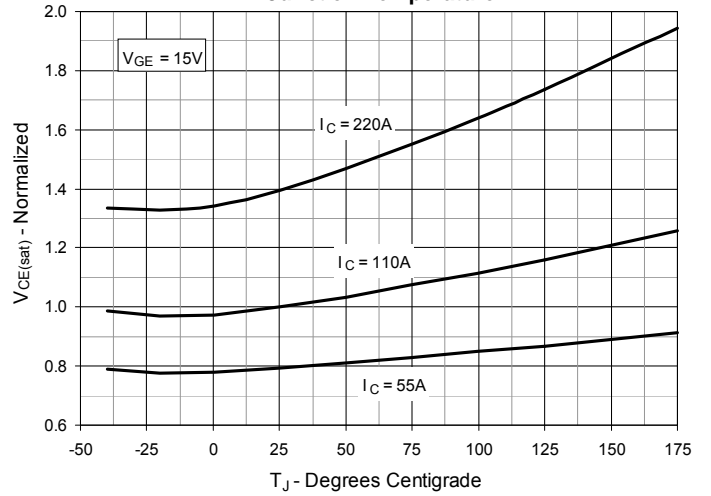
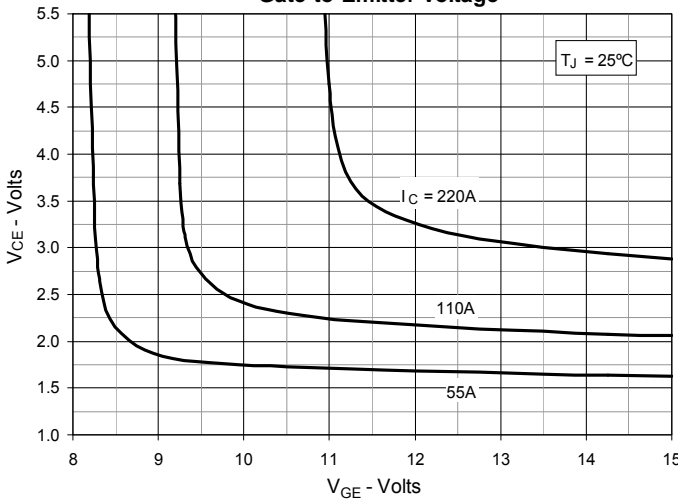
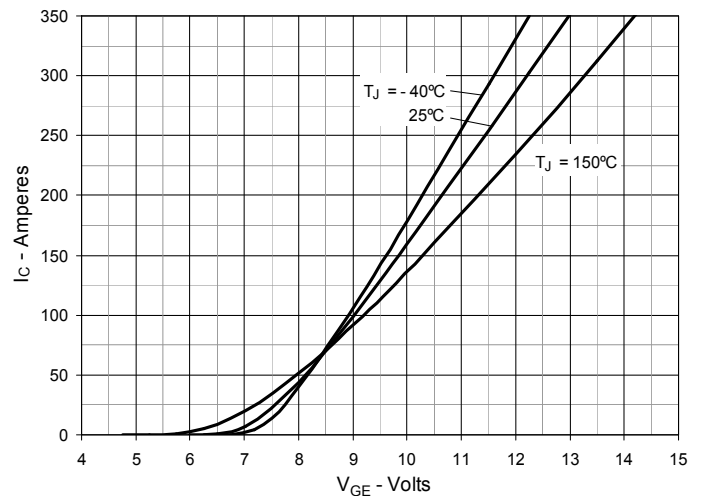
Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A <sub>1</sub>	2.2	2.54	.087	.102
A <sub>2</sub>	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b <sub>1</sub>	1.65	2.13	.065	.084
b <sub>2</sub>	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
∅P	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	.242	BSC

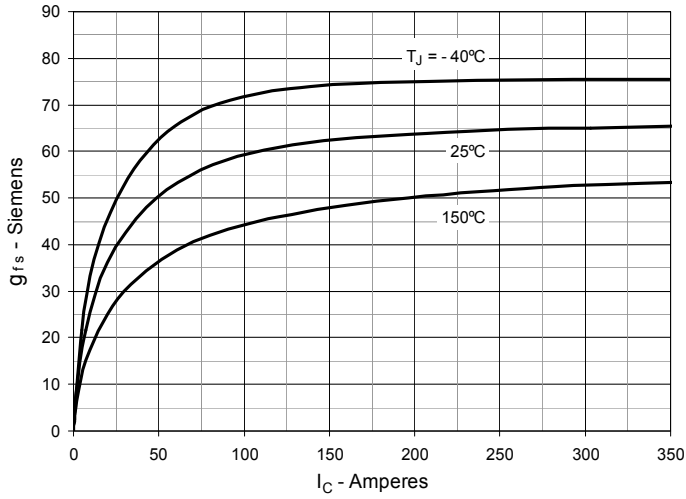
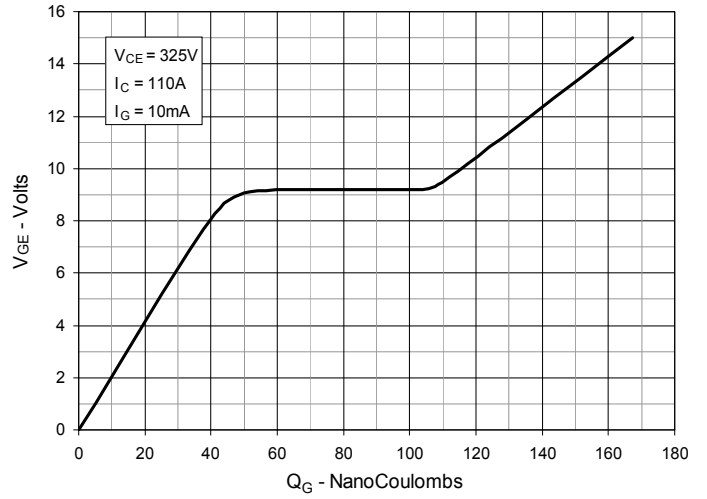
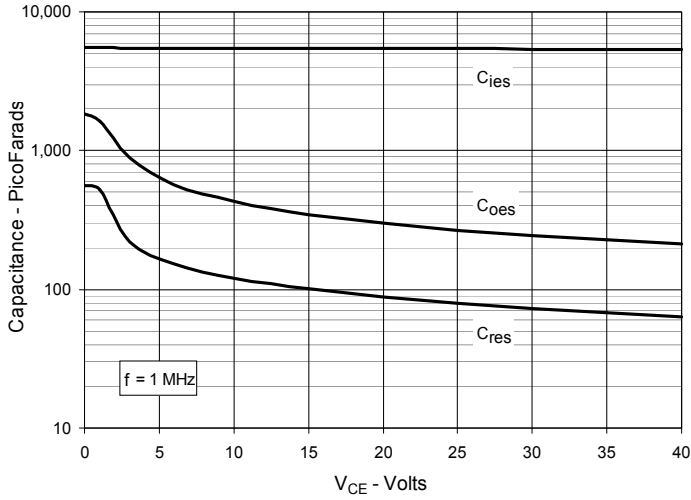
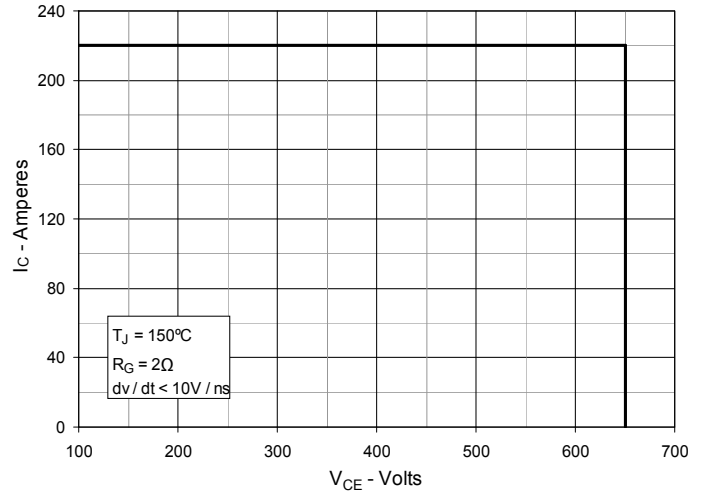
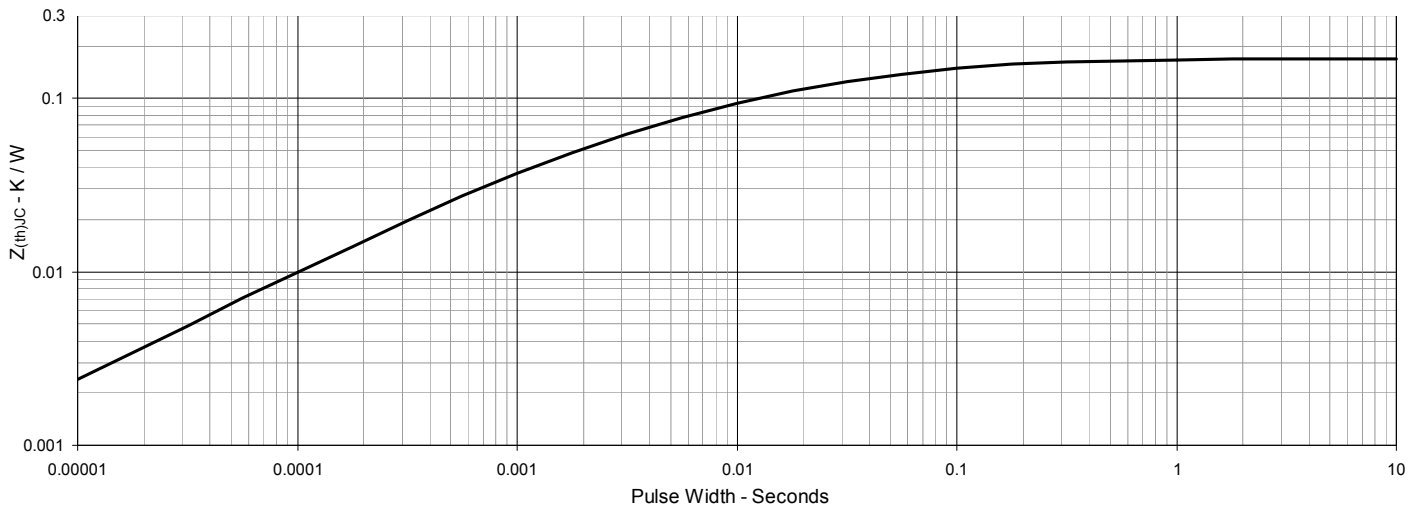
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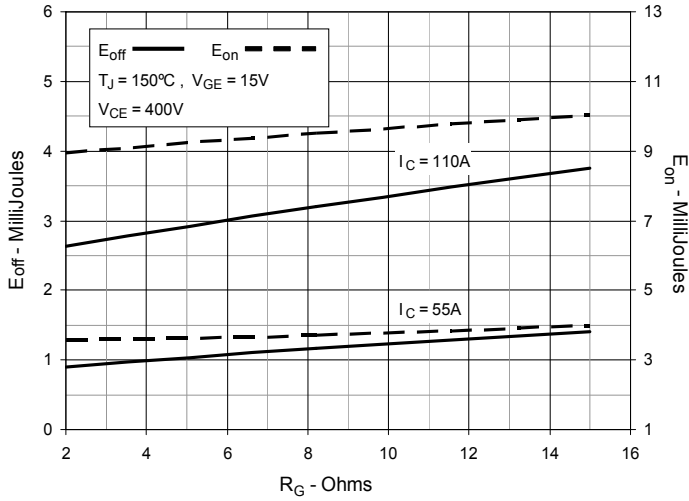
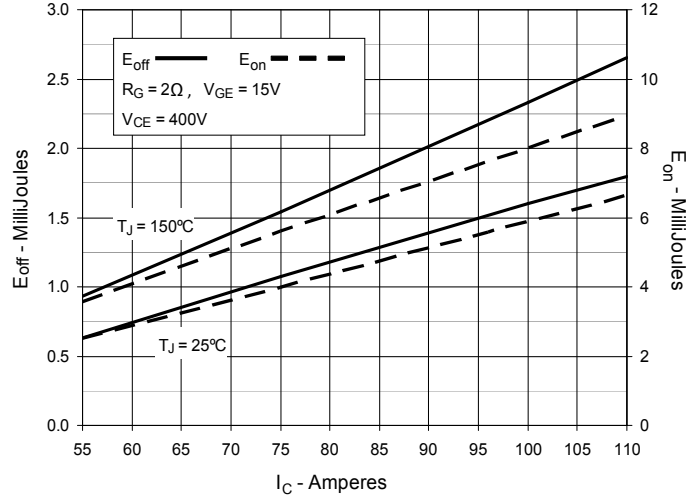
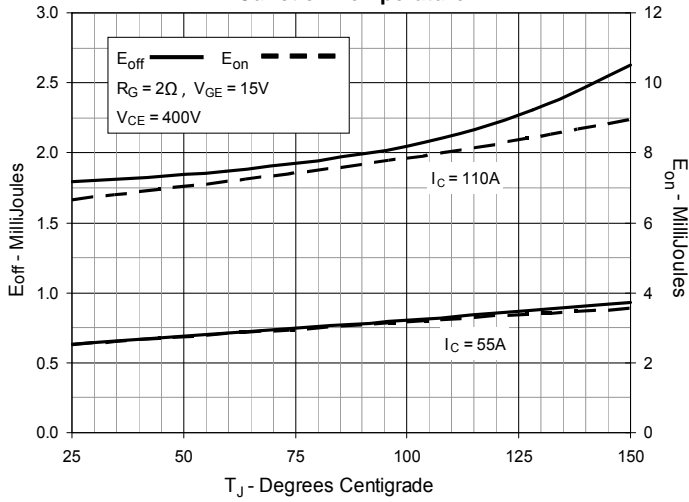
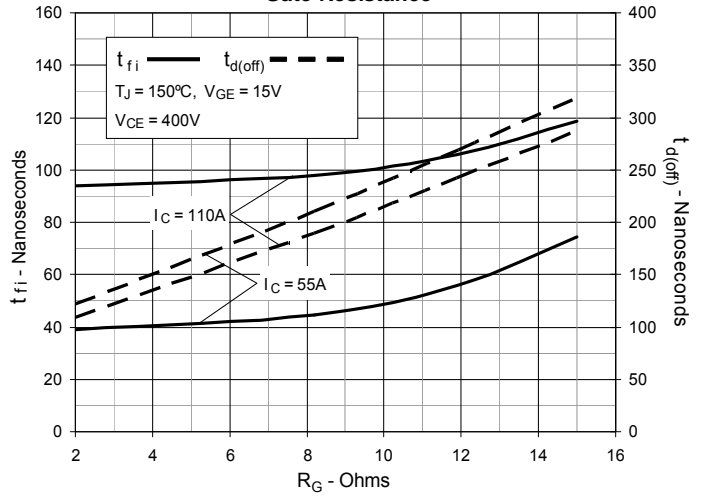
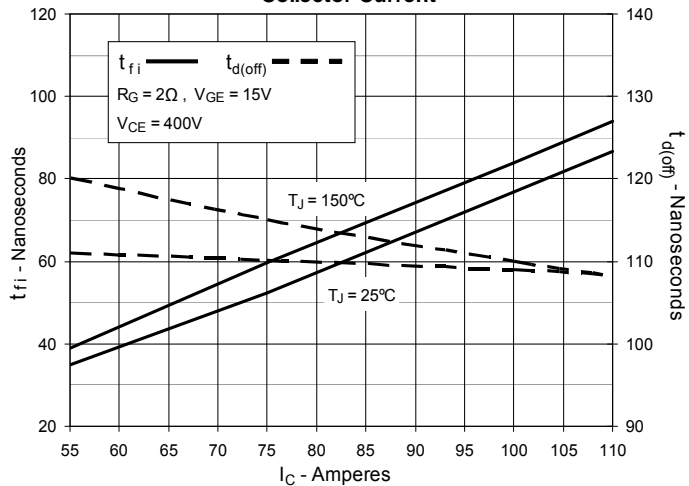
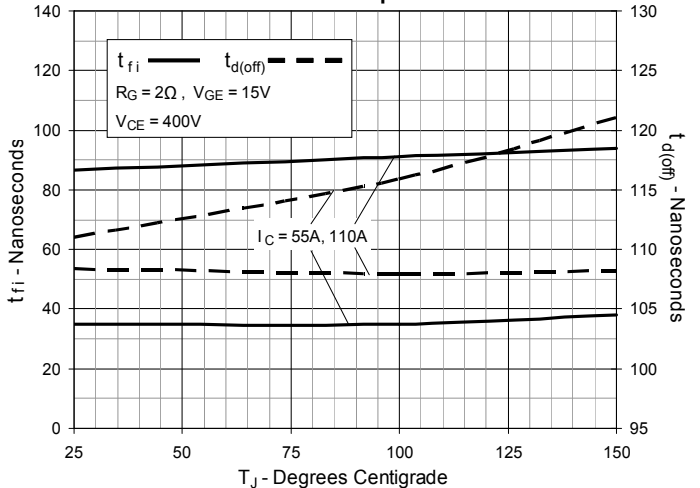
1. Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .
2. Switching times & energy losses may increase for higher  $V_{CE}$  (clamp),  $T_J$  or  $R_G$ .

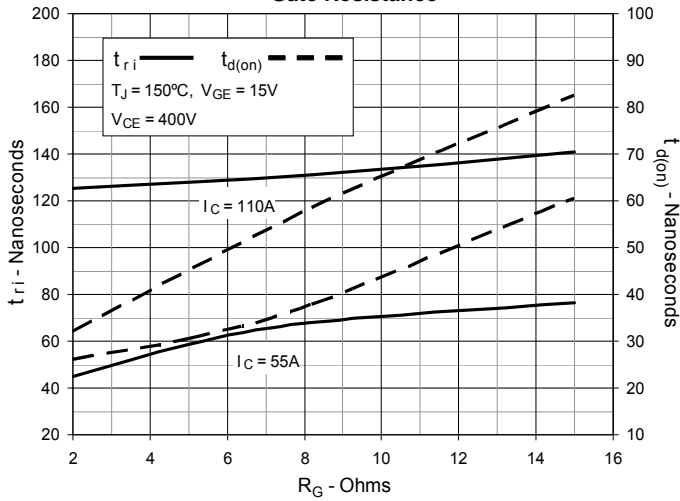
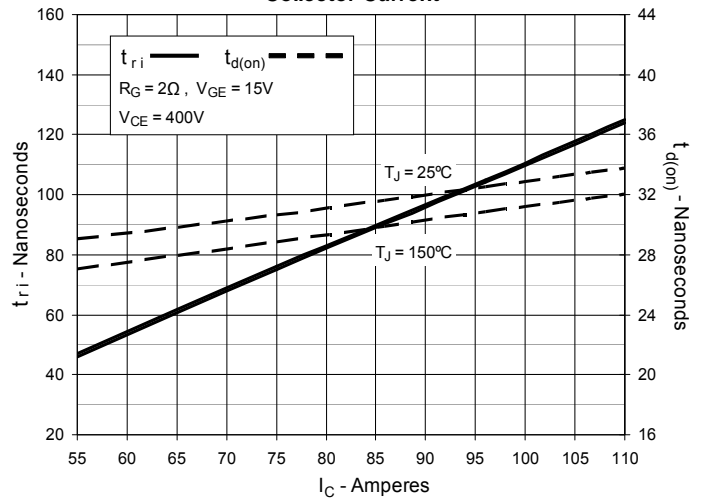
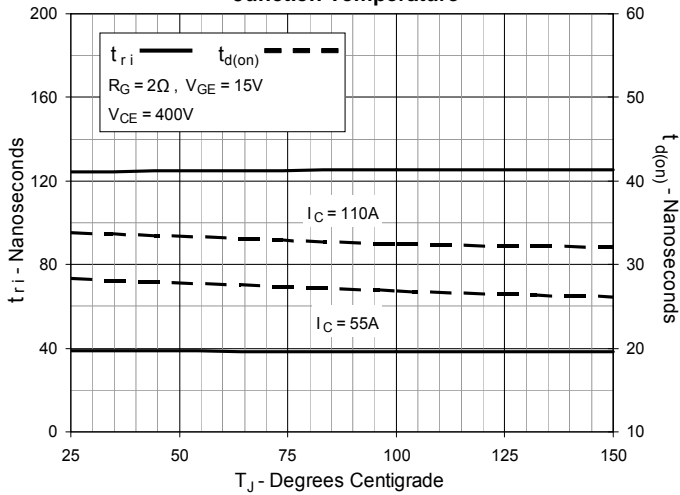
IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
	4,860,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

**Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$** 

**Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$** 

**Fig. 3. Output Characteristics @  $T_J = 150^\circ\text{C}$** 

**Fig. 4. Dependence of  $V_{CE(sat)}$  on Junction Temperature**

**Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage**

**Fig. 6. Input Admittance**


**Fig. 7. Transconductance**

**Fig. 8. Gate Charge**

**Fig. 9. Capacitance**

**Fig. 10. Reverse-Bias Safe Operating Area**

**Fig. 11. Maximum Transient thermal Impedance**


**Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance**

**Fig. 13. Inductive Switching Energy Loss vs. Collector Current**

**Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature**

**Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance**

**Fig. 16. Inductive Turn-off Switching Times vs. Collector Current**

**Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature**


**Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance**

**Fig. 19. Inductive Turn-on Switching Times vs. Collector Current**

**Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature**




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